

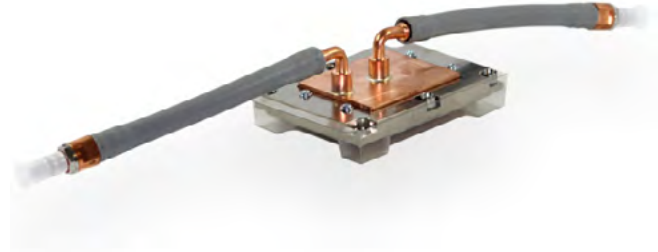
Datasheet - CPU/GPU Liquid Cold Plates



CPU & GPU LIQUID COLD PLATES

Liquid Cooling enables high heat transfer from CPU and GPU packages with low thermal resistance. By mounting liquid cold plates to high performance chips, heat is removed quickly and efficiently from sensitive components when installed in a complete liquid cooling system.

Boyd's Liquid Cold Plates for CPUs & GPUs consist of additional internal surface area for added heat transfer and aluminum mounting frame which enables high mounting forces while still maintaining structural integrity of the board. Boyd's cold plates come preassembled with Intel® Xeon® or AMD SP3 compatible hardware and pre-applied with thermal grease for fast installation.



ORDERING INFORMATION

Part Number	Mounting Configuration
668348	Intel® Xeon®
668359	AMD Rome SP3

Contact your Boyd representative for more information for our Liquid Cold Plates including additional mounting methods or arrangements.

Boyd offers a wide range of high performance cooling products for high-end computing systems from advanced air cooling systems, integrated two phase enhancements, and complete liquid cooling systems.

FEATURES AND BENEFITS

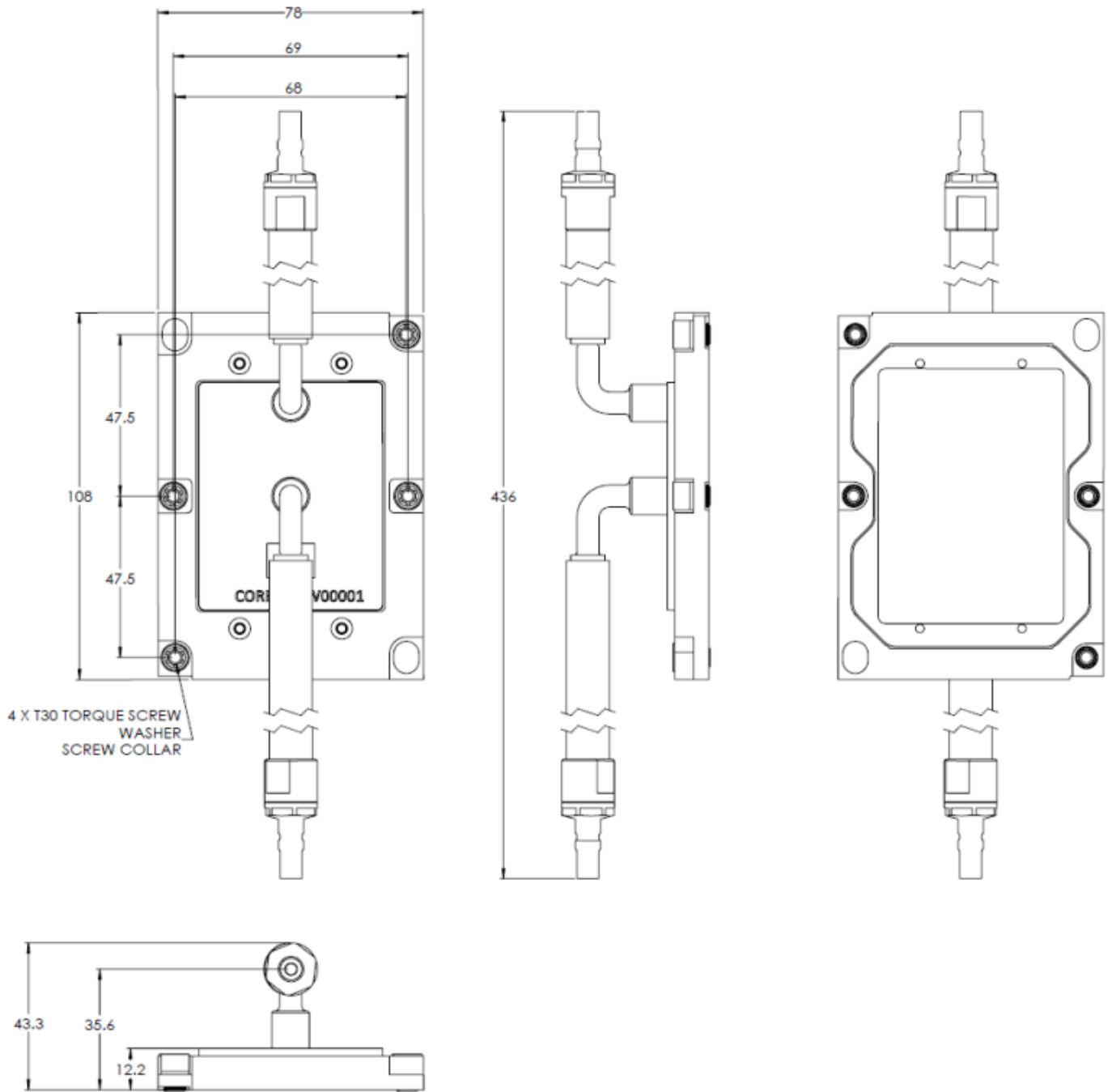
- Maximum Performance utilizing increased surface area for liquid cold plate to fluid heat transfer.
- High performance thermal grease pre-applied to base and shipped with individual protective grease shield.
- Pre-assembled with captive mounting hardware and ready for installation.
- High surface flatness combined with specialized thermal grease ensure minimum thermal interface resistance.

Boyd reserves the right to make changes to products or information contained herein without noticed. For additional information, please contact Boyd directly. *Intel and Xeon are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

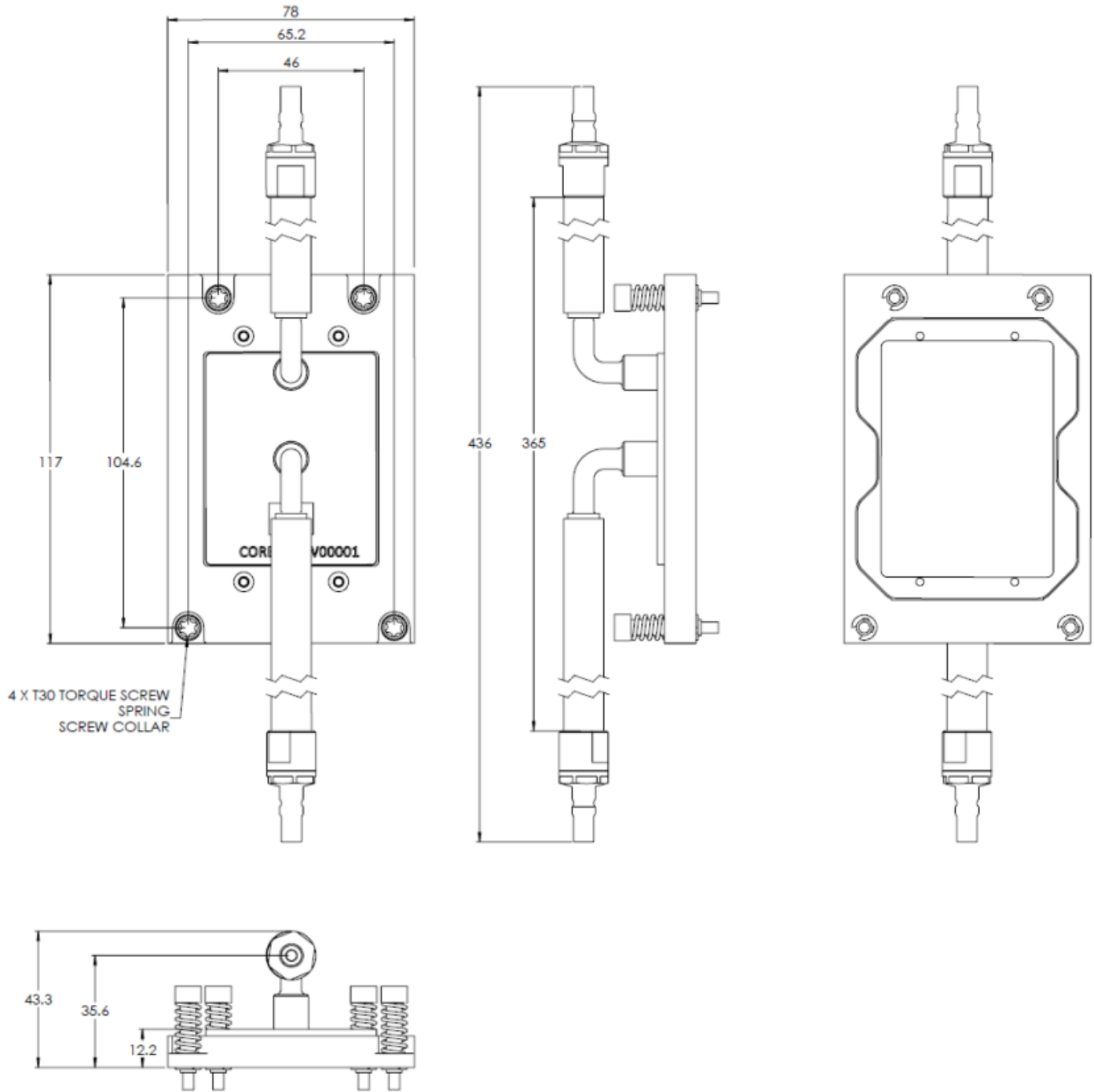
MECHANICAL

Drawing dimensions are shown in (mm)

Part Number: 668348



Part Number: 668359



PERFORMANCE GRAPH

